

## **REMARKS**

Claims 1 and 3-10 are now pending in the application. Claims 1, 6 and 7 are herein amended. Claims 8-10 are added herein. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

### **REJECTION UNDER 35 U.S.C. § 102**

Claims 6 and 7 stand rejected under 35 U.S.C. § 102(e) as being anticipated by Goto (U.S. Pat. No. 6,042,894). This rejection is respectfully traversed.

It is initially noted Claim 6 has been amended to recite in part:

“An anisotropic conductive adhesive agent for electrically connecting first terminals and second terminals, the second terminals being thicker than the first terminals” and

“wherein a particle diameter of the electrically conductive particles is smaller than a thickness of the first adhesive layer and the conductive particles are aligned at a terminal connection position within the conductive adhesive agent, the first adhesive layer adapted for application to the first terminals, and the second adhesive layer adapted for application to the second terminals”.

Claim 6 has also been amended to change [fixed] to “dispersed”.

It is initially noted Claim 7 has been similarly amended to recite in part:

“An anisotropic conductive adhesive agent for electrically connecting first terminals and second terminals, the second terminals being thicker than the first terminals” and

“wherein a particle diameter of the electrically conductive particles is smaller than a thickness of the first adhesive layer, and the electrically conductive particles are unevenly distributed along a second adhesive layer facing side of the first adhesive layer, the first adhesive layer adapted for application to the first terminals, and the second adhesive layer adapted for application to the second terminals”.

Claim 7 has also been amended to change [within] to “with”.

Goto appears to disclose a film-forming adhesive which is made by sticking electroconductive particles over a sticking layer and having a film-forming adhesive solution applied to fill the spaces between the particles. See column 17, lines 39-45. The sticking layer is incompatible with the film-forming adhesive, allowing the film to be “pressed against the surface of one of the circuits and peeled along the interface between the film-forming adhesive layer and the sticking layer.” See column 17, lines 51-58. The electrodes of both circuits are then positioned in alignment with each other and pressed or heated under pressure to electrically join them. See column 17, lines 59-62. Goto therefore discloses only a single conductive layer contacting both of two opposed groups of electrodes.

Goto does not disclose an anisotropic conductive adhesive agent for electrically connecting first and second terminals, the second terminal being thicker than the first, the first adhesive layer adapted for application to the first terminals, and the second adhesive layer adapted for application to the second terminals. Goto therefore cannot anticipate either amended Claim 6 or amended Claim 7. The Examiner is respectfully requested to withdraw the 35 U.S.C. § 102(e) rejection of Claims 6 and 7.

Claims 1 and 3-7 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Yamazaki (U.S. Pat. No. 4,696,764). This rejection is respectfully traversed.

In addition to the amendments noted above for Claims 6 and 7, it is initially noted Claim 1 has been amended to recite in part:

“An anisotropic conductive adhesive agent for electrically connecting first terminals and second terminals, the second terminals being thicker than the first terminals” and

“the first adhesive layer adapted for application to the first terminals; and the second adhesive layer adapted for application to the second terminals”.

Yamazaki appears to disclose an anisotropically conductive composition having a non-conductive base resin, a plurality of fine electrically conductive particles and a plurality of abrasive grain-like electrically conductive particles dispersed in the resin. See column 3, lines 47-64. The base resin is formed either by combining a curing agent with a catalyst or using a one-package type having a latent curing agent. See column 13, lines 20-26. The base resin can also be formed in two layers, one having a

thermosetting resin base and the other having a curing agent and a catalyst. See column 13, lines 32-35. The resin base, however, is used by either coating it in two layers or by separately coating each layer on facing circuit terminals. See column 13, lines 35-38.

Yamazaki does not disclose an anisotropic conductive adhesive agent for electrically connecting first and second terminals, the second terminal being thicker than the first, the first adhesive layer adapted for application to the first terminals, and the second adhesive layer adapted for application to the second terminals, wherein the first adhesive layer specifically includes a plurality of conductive particles. Yamazaki therefore cannot anticipate any of amended Claims 1, 6, or 7. The Examiner is respectfully requested to withdraw the 35 U.S.C. § 102(b) rejection of Claims 1 and 6-7.

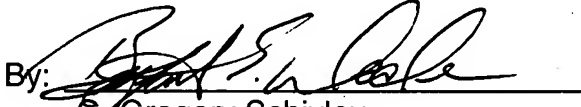
Because Claims 3-5 depend from amended Claim 1, Yamazaki cannot anticipate Claims 3, 4 or 5 for at least the same reasons as noted above for Claim 1. The Examiner is respectfully requested to withdraw the 35 U.S.C. § 102(b) rejection of Claims 3-5.

### CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

Dated: January 27, 2005

By:   
G. Gregory Schivley  
Reg. No. 27,382  
Bryant E. Wade  
Reg. No. 40,344

HARNESS, DICKEY & PIERCE, P.L.C.  
P.O. Box 828  
Bloomfield Hills, Michigan 48303  
(248) 641-1600

GGS/TJK/mmk